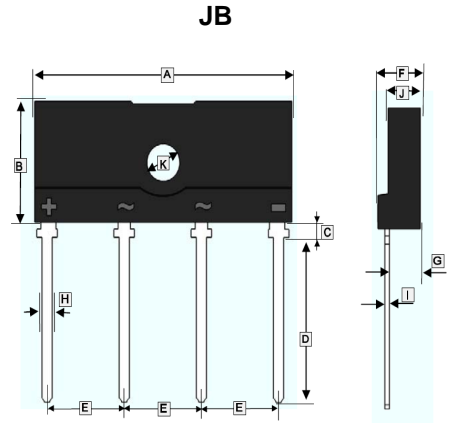


RoHS compliant product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- Ideal for printed circuit board
- Low forward voltage drop, high current capability
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	24.7	25.3	G	2.5	2.9
B	10.0	10.6	H	0.9	1.1
C	1.4(TYP.)		I	0.4	0.6
D	13.0	14.0	J	3.0	3.4
E	7.3	7.7	K	φ 3.2(TYP.)	
F	4.0	4.4			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, de-rate current by 20%.)

Parameter	Symbol	Rating	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	800	V
Average Rectified Output Current @60HZ sine wave, R-load	I_O	$T_C=131^\circ\text{C}$ (with heat sink)	6
		$T_A=25^\circ\text{C}$ (without heat sink)	1.8
Peak Forward Surge Current @ 60Hz sine wave, 1 cycle, $T_A=25^\circ\text{C}$	I_{FSM}	100	A
Maximum Peak Forward Voltage ³	V_{FM}	1.05	V
Peak Reverse Current ²	I_{RRM}	10	μA
Rating for fusing@ $1\text{ms} \leq t \leq 8.3\text{ms}$, per diode	I^2T	41.5	A^2S
Mounting Torque @ Recommend torque:5kg·cm	TOR	8	$\text{Kg} \cdot \text{cm}$
Dielectric Strength ¹	V_{dis}	2	kV
Typical Thermal Resistance (with heat sink)	$R_{\theta JC}$	1.5	$^\circ\text{C}/\text{W}$
Typical Thermal Resistance(without heat sink)	$R_{\theta JA}$	40	$^\circ\text{C}/\text{W}$
Typical Thermal Resistance(without heat sink)	$R_{\theta JL}$	6.5	$^\circ\text{C}/\text{W}$
Operating and Storage temperature range	T_J, T_{STG}	-55~150	$^\circ\text{C}$

Notes :

1. Terminals to case · AC 1 minute
2. $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode.
3. $I_{FM}=3\text{A}$, Pulse measurement, Rating of per diode

RATINGS AND CHARACTERISTIC CURVES

